



TITLE: HIGH-DENSITY PLASMA DEPOSITION PROCESS FOR FABRICATING  
A TOP CLAD FOR PLANAR LIGHTWAVE CIRCUIT DEVICES  
INVENTOR(S): Fan ZHONG, Jonathan G. BORNSTEIN  
USSN: 09/874,434 Attorney Docket #: LWM-A105

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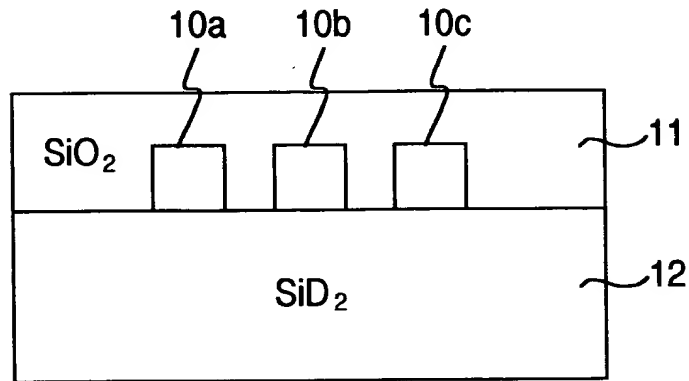


Fig. 1  
(Prior Art)



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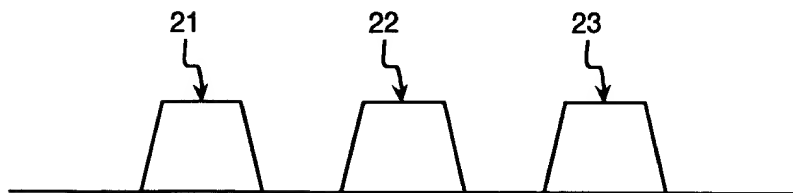


Fig. 2A  
(Prior Art)

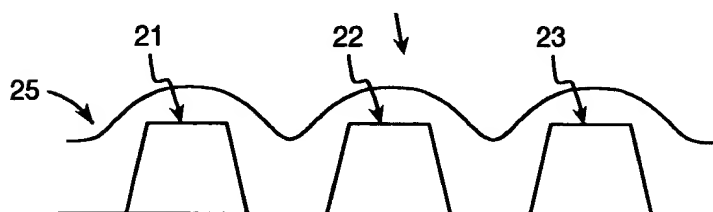


Fig. 2B  
(Prior Art)

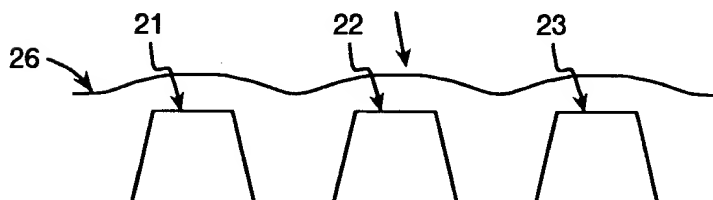


Fig. 2C  
(Prior Art)



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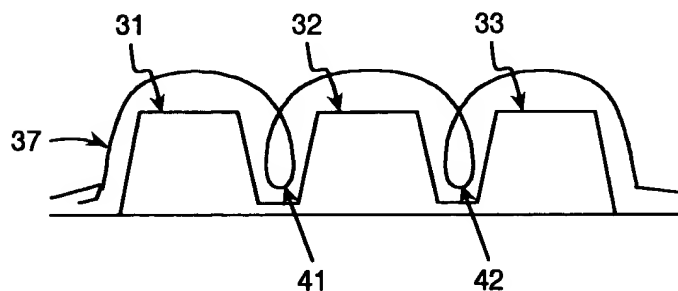


Fig. 3  
(Prior Art)

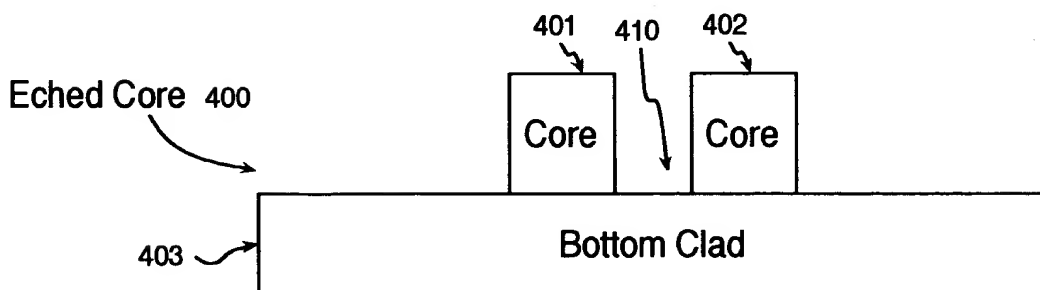


Fig. 4

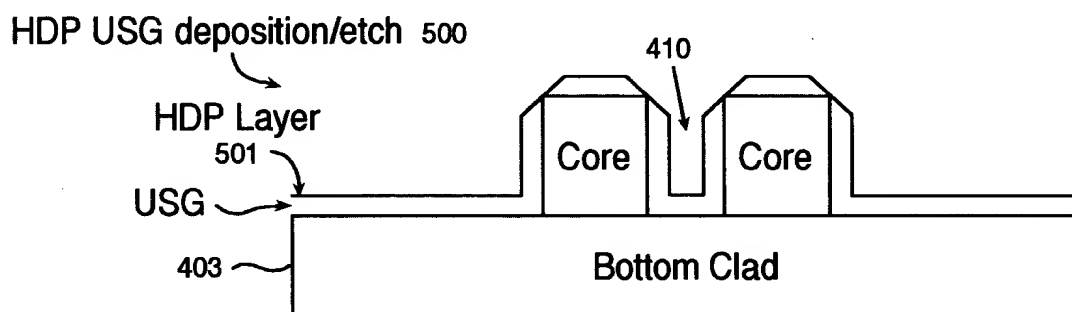


Fig. 5

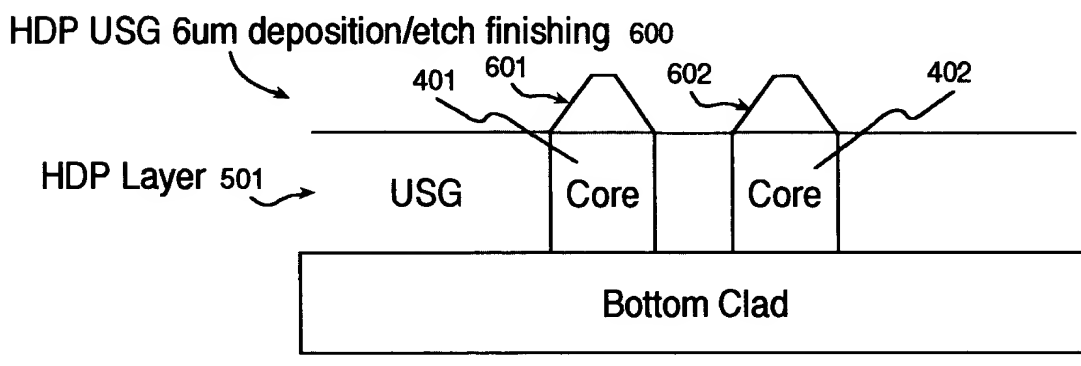


Fig. 6

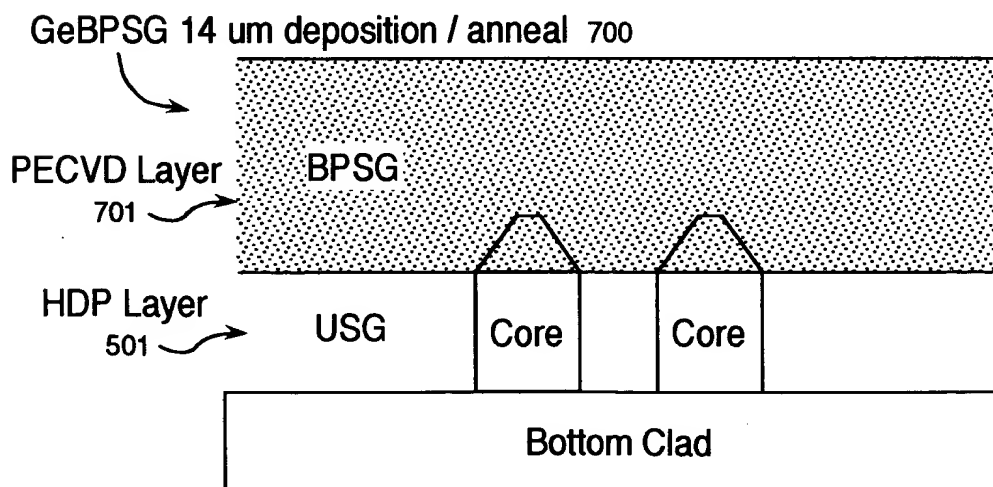


Fig. 7



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One Step HDP deposition  
and anneal (BPSG)  
with  
One Step PECVD deposition  
and anneal (BPSG)

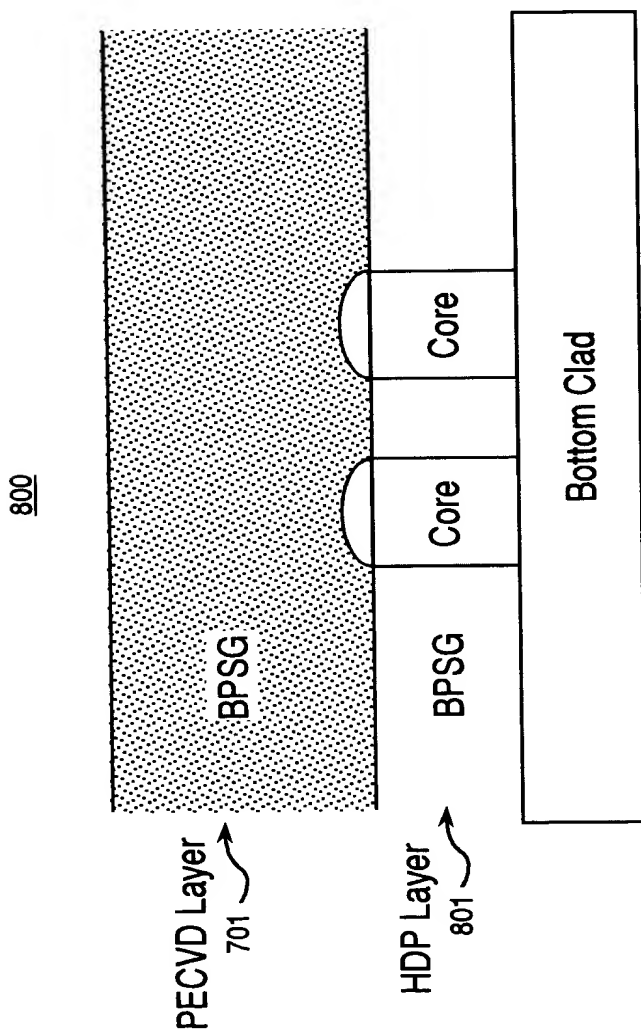


Fig. 8